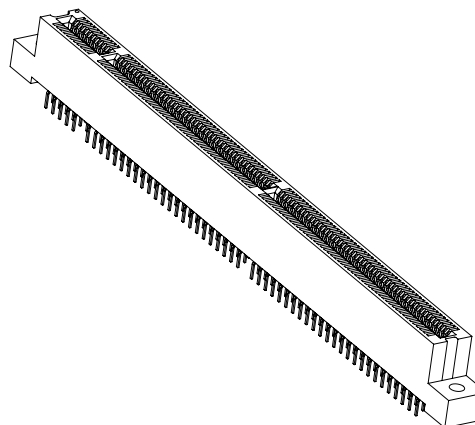




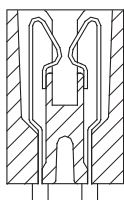
SPECIFICATIONS

- Accommodates .062" ± .008" [1.57 mm ± 0.20 mm] PC board (Consult factory for other board thicknesses)
- PPS or PA9T insulator
- Molded-in key available
- High reliability/high cycle hairpin bellow contacts
- 1 Amp current rating per contact for contacts fully energized
- UL Flammability Rating: 94V-0



High Density Card Edge

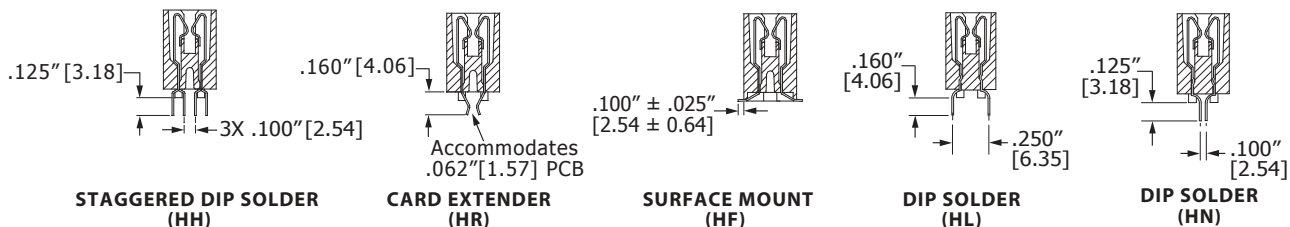
READOUT



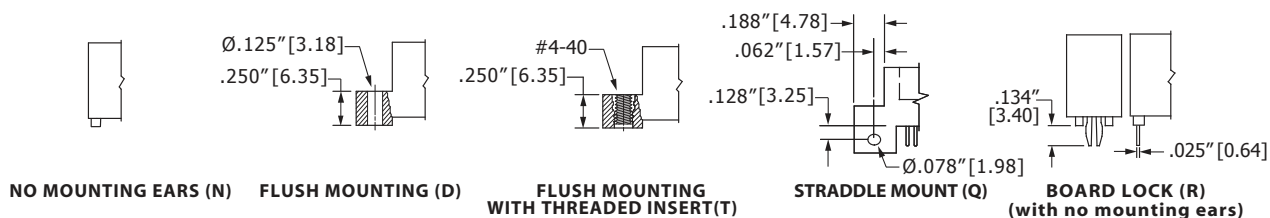
DUAL (D)

TERMINATION TYPE

Consult Factory for PC Board Layouts



MOUNTING STYLE





.050" [1.27 mm] Contact Centers, .610" [15.49 mm] Insulator Height, [MCA] Dip Solder/Card Extender/SMT

Industry Standard Part

High Density Card Edge

PART NUMBER OPTIONS

MATERIALS (INSULATOR/CONTACT)

- G = PA9T/Phosphor Bronze
- R = PPS/Phosphor Bronze
- J = PA9T/Beryllium Copper
- A = PPS/Beryllium Copper

Refer to Page 7 for Operating/Processing Temperatures

CONTACT FINISH - RoHS Compliant

All platings are Lead Free and have .000050" Nickel underplate

Contact Surface	Termination
B = .000010" Gold	.000100" Pure Tin, Matte
C = .000030" Gold	.000100" Pure Tin, Matte

CONTACT CENTERS

B = .050" [1.27 mm]

NUMBER OF CONTACT POSITIONS

56, 66, 91, 106

G B B 56 D HH D - S578

MODIFICATION (Consult Factory)

- S578 = Card Slot Barriers With Guide Posts
- S621 = Card Slot Barriers Without Guide Posts

MOUNTING STYLE

- N = No Mounting
- D = Flush Mounting
- T = Flush Mounting With Threaded Insert
- Q = Straddle Mount (Card Extender Only - Consult Factory)
- R = Metal Board Lock

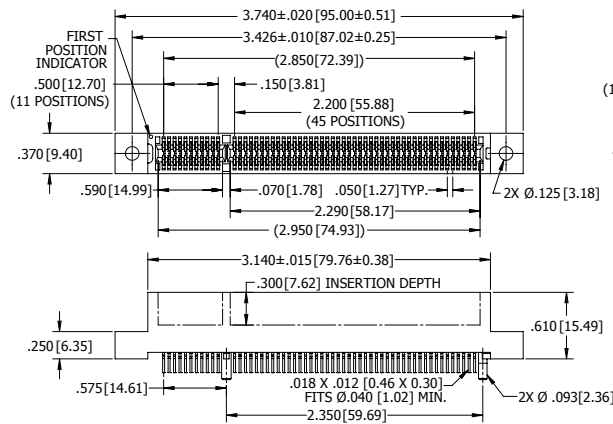
TERMINATION TYPE

- HH = Staggered Dip Solder
- HR = Card Extender
- HF = Surface Mount
- HL = .250" [6.35] X .160" [4.06] Dip Solder
- HN = .100" [2.54] X .125" [3.18] Dip Solder

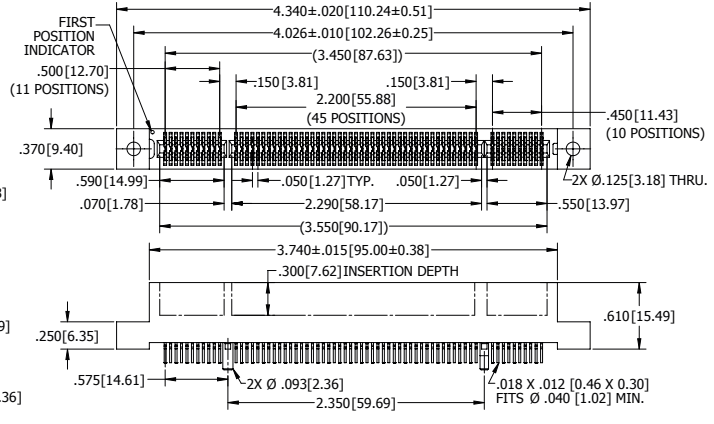
READOUT

D = Dual

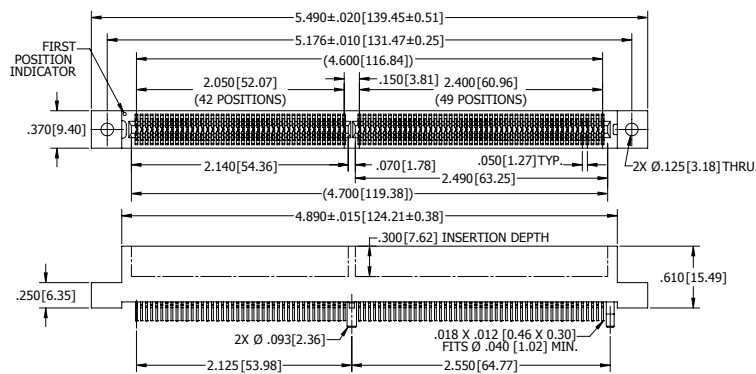
DIMENSIONS Dimensions in [] are in millimeters, all others are in inches.



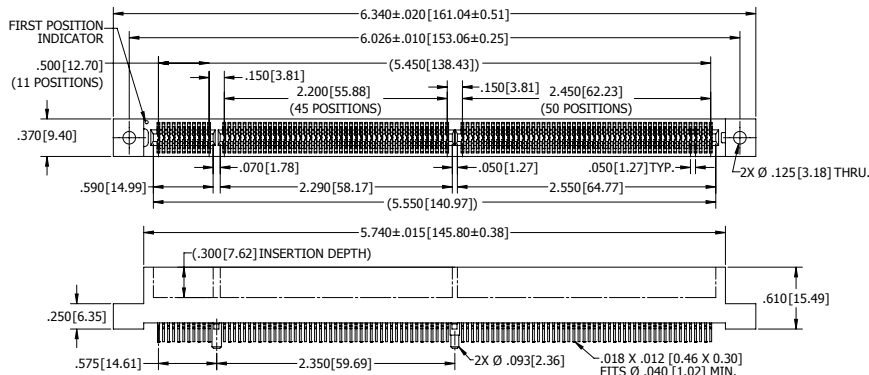
GBB56DHH-S578, 56 (11/45) POSITIONS



GBB66DHH-S578, 66 (11/45/10) POSITIONS



GBB91DHH-S578, 91 (42/49) POSITIONS



GBB106DHH-S578, 106 (11/45/50) POSITIONS